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PATENT
YOR920030206US1

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

In re Application of	:	Lawrence Shungwei Mok
Serial Number	:	10/784,624
Filing Date	:	02/23/2004
Examiner	:	Tho V. Duong
Group Art Unit	:	3744
For	:	HEAT DISSIPATION INTERFACE FOR SEMICONDUCTOR CHIP STRUCTURES

Sir:

In response to the Official Action dated June 23, 2009, please amend the above-identified application as follows:

In the Claims:

Cancel Claims 10 and 11 and add new Claims 12-20 therefore; and
amend Claims 1, 3 and 4, all as set forth in the Appendix A attached hereto.

REMARKS

Applicant has amended Claims 3 and 4 to make them dependent upon Claim 1. Claims 11 and 12 have been canceled to obviate the rejection under 35 U.S.C. §112, first paragraph. Claim 1 has been amended in a good faith effort to obviate the rejections under 35 U.S.C. §112, second paragraph.